



Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

<b>PCN #:</b> <b>A0710-01</b> <b>DATE:</b> <b>13-Nov-2007</b> <b>Product Affected:</b> 20mm x 20mm TQFP-144 (Standard and Green) Refer to Attachment II for the affected part numbers <b>Date Effective:</b> <b>13-Feb-2008</b>	<b>MEANS OF DISTINGUISHING CHANGED DEVICES:</b> <input type="checkbox"/> Product Mark <input checked="" type="checkbox"/> Back Mark      Lot # will have a "UT" prefix <input type="checkbox"/> Date Code <input type="checkbox"/> Other
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<b>Contact:</b> Geoffrey Cortes <b>Title:</b> Product Quality Assurance <b>Phone #:</b> (408) 284-8321 <b>Fax #:</b> (408) 284-1450 <b>E-mail:</b> <a href="mailto:Geoffrey.Cortes@idt.com">Geoffrey.Cortes@idt.com</a>	<b>Attachment:</b> <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No  <b>Samples:</b> Please contact your local sales representative for sample request & availability.
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**DESCRIPTION AND PURPOSE OF CHANGE:**

<input type="checkbox"/> Die Technology <input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Assembly Process <input type="checkbox"/> Equipment <input type="checkbox"/> Material <input type="checkbox"/> Testing <input checked="" type="checkbox"/> Manufacturing Site <input type="checkbox"/> Data Sheet <input type="checkbox"/> Other	<p>This notification is to advise our customers that IDT is changing the assembly of 20mm x 20mm TQFP-144 both standard and green version from AMKOR, Philippines and ASAT China to UTAC, Singapore. There is no change to the moisture performance of these packages.</p> <p>Attachment I details the qualification data for this change and Attachment II shows the affected list of part numbers.</p>
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**RELIABILITY/QUALIFICATION SUMMARY:**

Refer to qualification data shown in attachment I.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <b><i>Approval for shipments prior to effective date.</i></b>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

**CUSTOMER COMMENTS:** \_\_\_\_\_

\_\_\_\_\_

\_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_                      DATE: \_\_\_\_\_



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### ATTACHMENT I - PCN # : A0710-01

**PCN Type:** Manufacturing Site - Change of Assembly Location

**Data Sheet Change:** None

No change in moisture sensitivity level (MSL)

#### Detail Of Change:

This notification is to advise our customers that IDT is changing the assembly of 20mm x 20mm TQFP 144 both standard and green version from AMKOR, Philippines and ASAT, China to UTAC Singapore. There is no change to the moisture performance of these packages using the assembly material set as listed in the tables under each group.

There is no change in the moisture sensitivity level (MSL).

Attachment II shows the affected part numbers.

#### Sample Availability:

Samples for each package type are available for customer evaluation, but may not be available for all devices.

Please contact your local IDT sales representative for your sample request and availability.



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### ATTACHMENT I - PCN # : A0710-01

**Qualification Information and Qualification Data:**

**Affected Packages:** TQFP  
20mm x 20mm 144L (DA/DAG packages)

**Assembly Material:** See Table below

Description	Existing	Add
Assembly Location	AMKOR, Philippines & ASAT China	UTAC, Singapore
Assembly Materials	Die Attach: Ablestik 3230	3230
	Wire: Au wire	Au wire
	Mold Compound: EME-G700L	G700LY
	Lead Frame: Copper Alloy	Copper Alloy
	Plating: Sn/Pb (standard) and matte 100% Sn (green)	Sn/Pb (standard) and matte 100% Sn (green)

**Qualification Plan #:** P07-10-02  
**Test Vehicle:** 20mm x 20mm TQFP-144  
**Qualification Test Plan and Results:**

Test Description	Test Method	Test Results (SS/Rej)
* Temperature Cycling (Cond B, 1000 cycles)	JESD22-A104	135/0
* Auto Clave (121°C, 100% RH, 96 hours)	JESD22-A102	135/0
Unbiased HAST (130 °C, 85% RH Unbiased, 50 hours)	JESD22-A118	135/0
High Temperature Stabilization Bake (150 °C, 1000 hours)	JESD22-A103	135/0

**Notes:** \* Test requires moisture pre-conditioning sequence per JESD22-A113.



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## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT II - PCN # : A0710-01

#### Affected Part Number

Part Number	Part Number	Part Number
IDT82V2048DA	IDT82V2048SDA	IDT82V2058LDA
IDT82V2048DAG	IDT82V2048SDAG	IDT82V2058LDAG
IDT82V2048LDA	IDT82V2058DA	IDT82V2058XDA
IDT82V2048LDAG	IDT82V2058DAG	IDT82V2058XDAG

Notes: For T & R (shipping method) "8" suffix is added to the IDT part# respectively.